CSTIC 10 Year Anniversary

十年纪念

Committee & Semi China Teams

Prepared by David Huang. March 2019
CSTIC 10 Year Anniversary

- CSTIC was initiated in 2009 with Semi and ECS as the organizers, source from ISTC (since 2000), and tested as CSMIC (2008). A Semiconductor technical forum to bridge China and the World. Volunteer committee team, open, transparent, passion.

- Influential conference. Papers from 230 to 400, attendee from 300 ~800, nine symposia to cover the IC manufacturing flow, ~80 committee members around the World. Panel discussions, training, poster... International organizers: Semi, imec, IEEE.

- Focus on manufacturing technology, speakers from: Intel, Samsung, TSMC, Global Foundries, SMIC, imec, AMAT, TEL, Stanford, MIT, Beijing University…. 

- Distinguished plenary speakers: Four Nobel Laureate speakers so far: Georg Bednorz (2009), Leo Esaki (2011), Ivar Giaever (2013), Hiroshi Amano (2017), VP or fellow from Intel, TSMC, IBM, SMIC, Huawei. Excellent invited speakers from established world class experts.

- Together, we continuously work with industry in semiconductor golden period & region

We Did It. 我们做到了！
2008, Warm Up as CSMIC, Shanghai, Intercontinental Hotel

梦想，热情，团队。
CSMIC 2008 Technical Committee

SEMI Inc. – Organizer / Financial Support
China High Tech Materials Group - Organizer

CSMIC Executive Committee – Technical organizer

CSMIC Divisions
I.) Integration
II.) Lithography
III.) CMP & Clean
IV.) Thin Film
V.) Packaging
VI.) Emerging materials

CSMIC technical committee consists of area experts and they are all volunteers like other major technical conferences in the world.

Conference Executive Committee

<table>
<thead>
<tr>
<th>Name</th>
<th>Position</th>
<th>Company/Location</th>
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<tbody>
<tr>
<td>Dr. David Huang</td>
<td>Chairman Director</td>
<td>Praxair Inc., USA</td>
</tr>
<tr>
<td>Mrs. Shi Ying</td>
<td>Co-Chair Director</td>
<td>Gritek, China</td>
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<tr>
<td>Dr. Hanming Wu</td>
<td>Technical Director</td>
<td>SMIC, China</td>
</tr>
<tr>
<td>Dr. Qingyuan Han</td>
<td>Co-Chair President</td>
<td>Hans Consulting, USA</td>
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<tr>
<td>Mrs. April Peng</td>
<td>Secretary Chief Editor</td>
<td>Semi China</td>
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Session I. New Materials and Process Integration

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<tr>
<td>Dr. Hanming Wu</td>
<td>Chairman Technical Director</td>
<td>SMIC, China</td>
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<tr>
<td>Dr. Youfan Lui</td>
<td>Co-Chair Chairman</td>
<td>CASPA Phenix USA</td>
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Session II. Photolithography

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<tr>
<td>Dr. Cindy Chen</td>
<td>Chairperson President</td>
<td>Kempur, China</td>
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<tr>
<td>Dr. Curtis Liang</td>
<td>Co-chair Manager</td>
<td>ASML-China</td>
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Session III. CMP & Cleaning

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<tr>
<td>Dr. Chris Yu</td>
<td>Chairman CEO</td>
<td>Anji Microelectronics</td>
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<tr>
<td>Dr. Kuochun Wu</td>
<td>Co-chair Director</td>
<td>Cabot Micorelectronics Inc</td>
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Session IV. Thin Film, Etch and Plating

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<tr>
<td>Dr. WeiE Wang</td>
<td>Chairman Scientist</td>
<td>Intel Inc</td>
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<tr>
<td>Dr. Fei Xue</td>
<td>Co-chair Director</td>
<td>ATMI Inc</td>
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Session V. Packaging Materials

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<tr>
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<tr>
<td>Dr. Wei Chen</td>
<td>Chairman Manager</td>
<td>Dow Corning, China</td>
</tr>
<tr>
<td>Mr. Han Jianglong</td>
<td>Co-chair President</td>
<td>Henkel Huawei, China</td>
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Session VI. Emerging and Special Materials

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<tr>
<td>Dr. Qinghuang Lin</td>
<td>Chairman Scientist</td>
<td>IBM, USA</td>
</tr>
<tr>
<td>Dr. Renhe Jia</td>
<td>Co-chair Sr. Engineer</td>
<td>Applied Materials, USA</td>
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Scope of the Conference
China Semiconductor Technology International Conference - CSTIC
中国半导体技术国际会议

Device Design 晶片设计
- layout materials requirement
  提出对材料的构想

Materials 材料
- Basic elements to form a device
  基础研究
Fundamental
制造生产
Manufacturing
Application
工业应用

Processes 工艺流程
- Integrate the materials
  组合材料

Tooling 设备装置
- Plate form to integrate materials
  材料组合的平台
2009, Initiated CSTIC from ISTC with Semi & ECS, Sheraton

千里之行，始于脚下；国际化，制度化。
2010, Good Speakers, Nice Team

学到了东西，认识了朋友。好开心！
2011, Found Home (Kerry Hotel), Nice Place.

好地方，好团队
2012，Understand Quantum Tunneling

Esaki Tunnel Diode, 当年轻人面对诺贝尔偶像时

一流的讲师，论文走向世界
2014, Moved to SHICC

新家，上海国际会议中心
2015, Consistently Focus on Manufacturing Technology
2016, Post Moore’s Law - What will be the path?

When will Moore’s Law end?
- Moore’s Law NEVER ends. Because....

- Innovative products following or speeding up Moore’s Law will gain market share and "DISRUPT" others
- Products lagging behind Moore’s Law will be "DISRUPTED" and fade away from market
- The way we will continue to change as long as...

摩尔定律到头了吗？
2017, Partner with imec. Memory Chip Market Booming
2018，EUV, FinFET Enabled Sub 10nm Node

EUV, 鱼翅设计(FinFET)延长了摩尔定律。
CSTIC 2019, 2029, 39… Technology is Driving Industries

Data centers / IoT

5G Network / Devices

Artificial Intelligence

IC Chip Essential

高科技引领生产力，我们是幸运的一代